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FAIRCHILD SEMICONDUCTOR®

July 2010

FDMC86240

N-Channel Power Trench® MOSFET

150 V, 16 A, 51 mΩ

Features

- Max $r_{DS(on)}$ = 51 mΩ at V_{GS} = 10 V, I_D = 4.6 A
- Max $r_{DS(on)}$ = 70 mΩ at V_{GS} = 6 V, I_D = 3.9 A
- Low Profile - 1 mm max in Power 33
- 100% UIL Tested
- RoHS Compliant

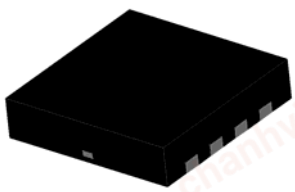
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

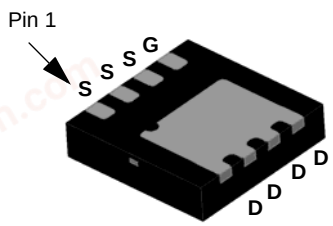
Application

- DC - DC Conversion

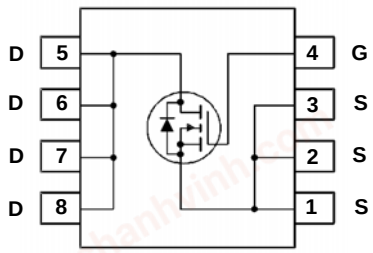
Top



Bottom



MLP 3.3x3.3



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			150	V
V_{GS}	Gate to Source Voltage			±20	V
I_D	Drain Current -Continuous (Package limited)	T_C = 25 °C		16	A
	-Continuous (Silicon limited)	T_C = 25 °C		19	
	-Continuous	T_A = 25 °C	(Note 1a)	4.6	
	-Pulsed			20	
E_{AS}	Single Pulse Avalanche Energy		(Note 3)	34	mJ
P_D	Power Dissipation	T_C = 25 °C		40	W
	Power Dissipation	T_A = 25 °C	(Note 1a)	2.3	
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC86240	FDMC86240	Power 33	13 ”	12 mm	3000 units

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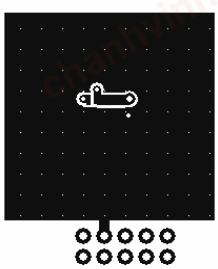
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Electrical Characteristics T_J = 25 °C unless otherwise noted

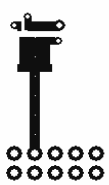
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		101		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 120 V, V_{GS} = 0 V			1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA	2.0	2.9	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		-9		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 4.6 A		44.7	51	mΩ
		V_{GS} = 6 V, I_D = 3.9 A		51.4	70	
		V_{GS} = 10 V, I_D = 4.6 A, T_J = 125 °C		84.5	97	
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 4.6 A		15		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 75 V, V_{GS} = 0 V, f = 1 MHz		680	905	pF
C_{oss}	Output Capacitance			79	105	pF
C_{rss}	Reverse Transfer Capacitance			4.3	10	pF
R_g	Gate Resistance			0.5		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 75 V, I_D = 4.6 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		8.2	17	ns
t_r	Rise Time			1.7	10	ns
$t_{d(off)}$	Turn-Off Delay Time			14	26	ns
t_f	Fall Time			3.1	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 0 V to 10 V; V_{DD} = 75 V, I_D = 4.6 A		11	15	nC
$Q_{g(TOT)}$	Total Gate Charge	V_{GS} = 0 V to 5 V; V_{DD} = 75 V, I_D = 4.6 A		6	9	nC
Q_{gs}	Total Gate Charge	V_{DD} = 75 V, I_D = 4.6 A		2.8		nC
Q_{gd}	Gate to Drain “Miller” Charge	V_{DD} = 75 V, I_D = 4.6 A		2.3		nC
Drain-Source Diode Characteristics						
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 4.6 A (Note 2)		0.79	1.3	V
		V_{GS} = 0 V, I_S = 2 A (Note 2)		0.75	1.2	
t_{rr}	Reverse Recovery Time	I_F = 4.6 A, di/dt = 100 A/μs		58	93	ns
Q_{rr}	Reverse Recovery Charge			63	102	nC

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



53 °C/W when mounted on a 1 in^2 pad of 2 oz copper



125 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.

3. Starting T_J = 25 °C; N-ch: L = 3 mH, I_{AS} = 4.8 A, V_{DD} = 150 V, V_{GS} = 10 V.

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Typical Characteristics T_J = 25 °C unless otherwise noted

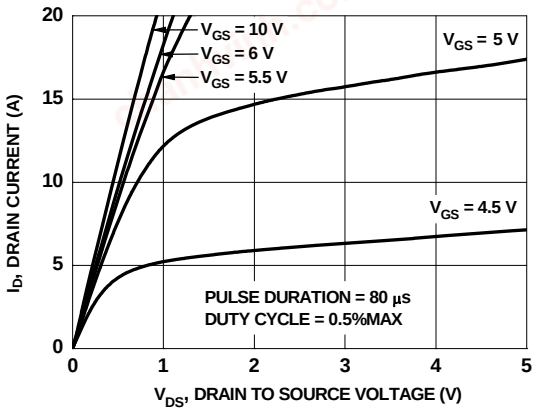


Figure 1. On-Region Characteristics

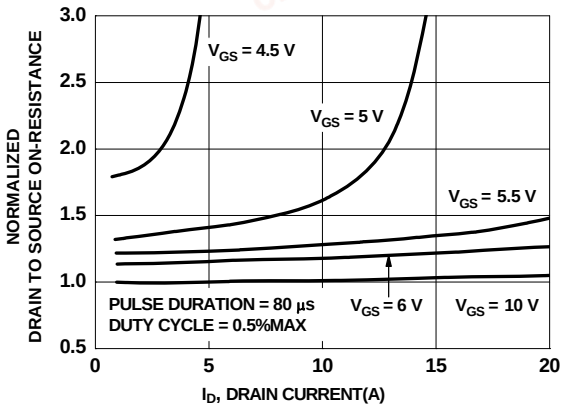


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

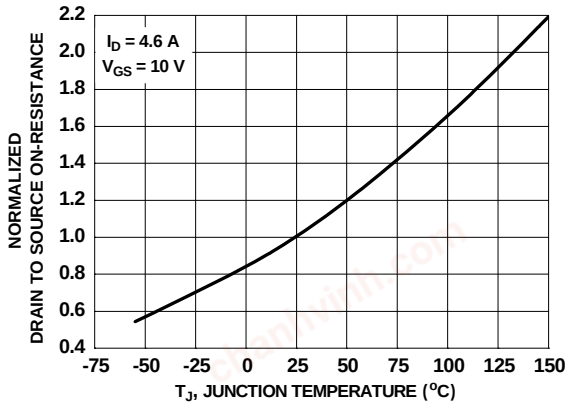


Figure 3. Normalized On-Resistance vs Junction Temperature

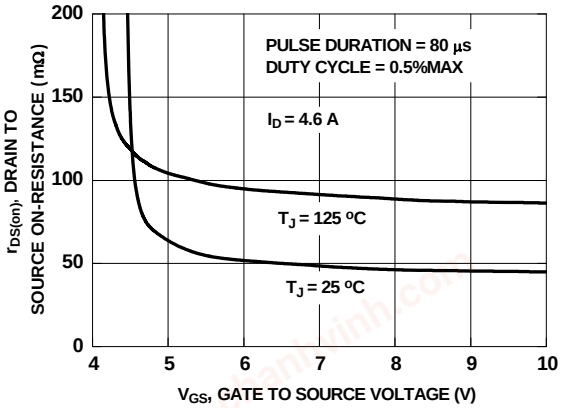


Figure 4. On-Resistance vs Gate to Source Voltage

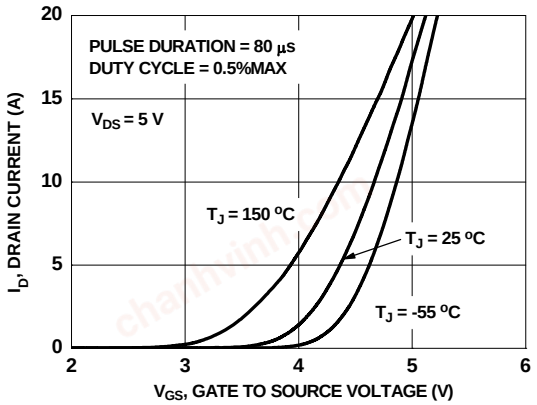


Figure 5. Transfer Characteristics

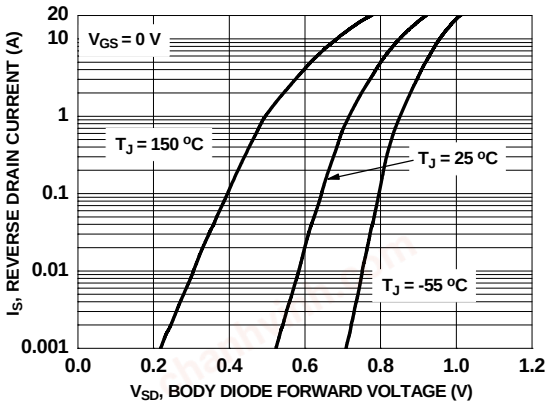


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

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Typical Characteristics T_J = 25 °C unless otherwise noted

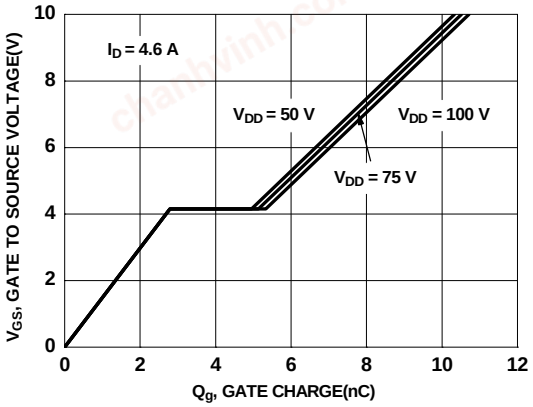


Figure 7. Gate Charge Characteristics

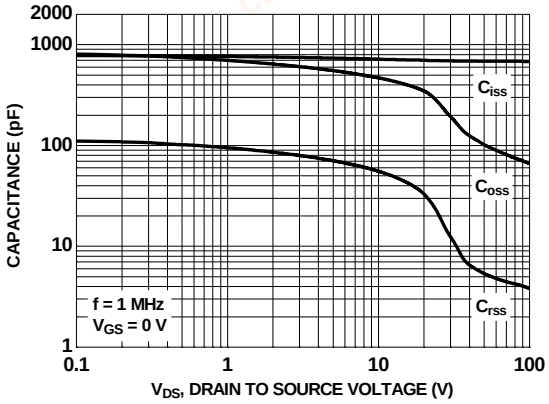


Figure 8. Capacitance vs Drain to Source Voltage

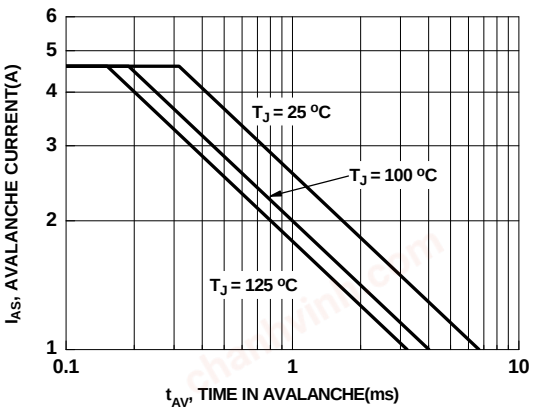


Figure 9. Unclamped Inductive Switching Capability

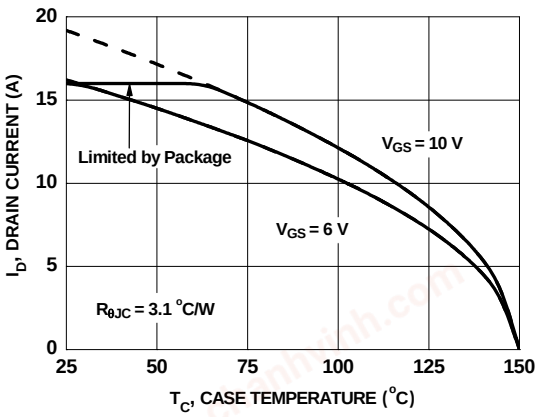


Figure 10. Maximum Continuous Drain Current vs Case Temperature

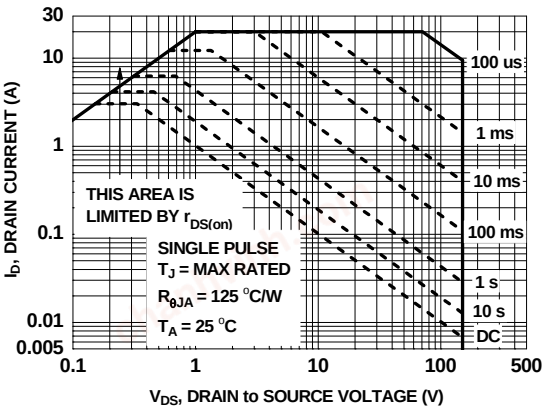


Figure 11. Forward Bias Safe Operating Area

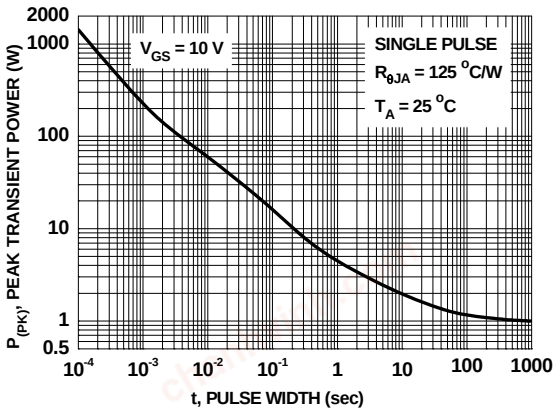


Figure 12. Single Pulse Maximum Power Dissipation

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Typical Characteristics T_J = 25 °C unless otherwise noted

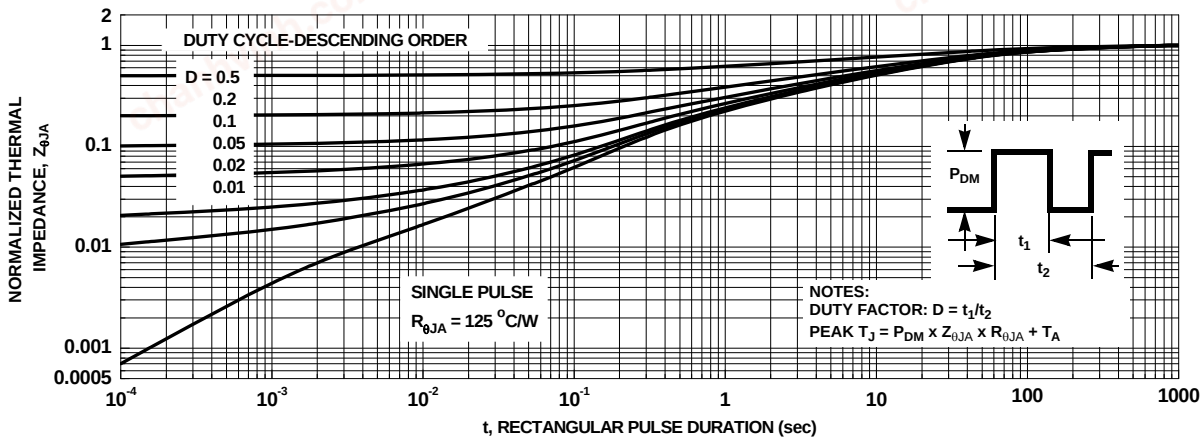
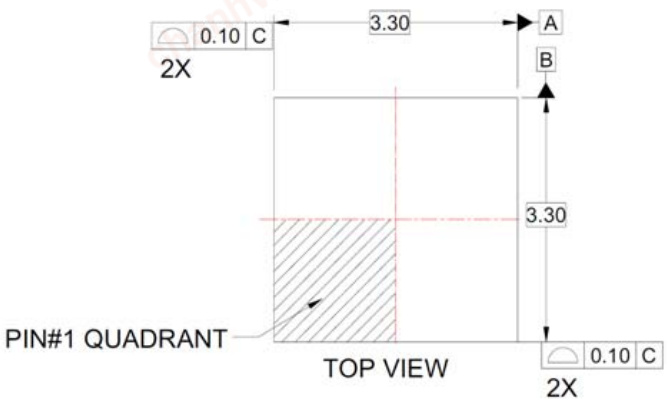
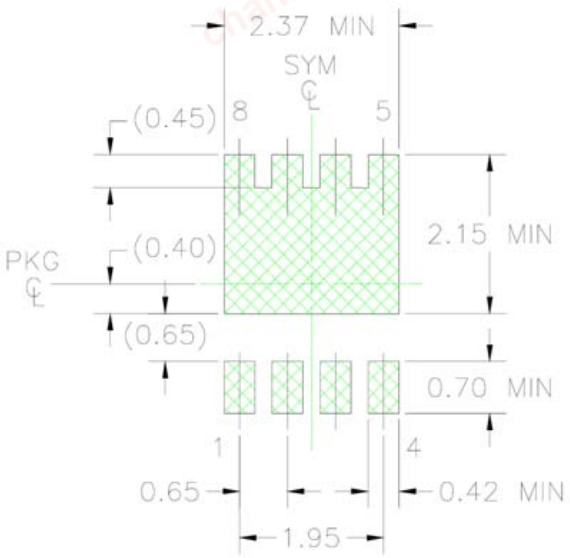


Figure 13. Transient Thermal Response Curve

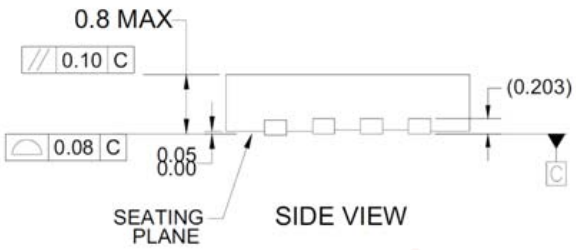
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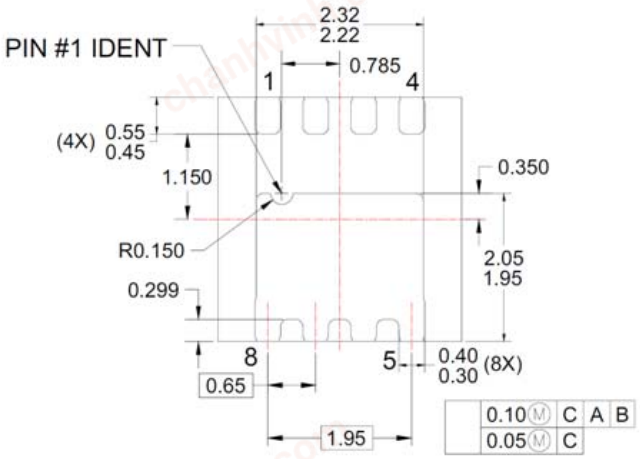
Dimensional Outline and Pad Layout





RECOMMENDED LAND PATTERN





BOTTOM VIEW

NOTES:

A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

D. DRAWING FILE NAME : MLP08SREVA

E. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY

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